

Soder-Wick® Lead-Free Desoldering Braid

Product Description

Soder-Wick Lead-Free is the state of the art in desoldering technology. It is specially designed for removal of today's high temperature lead-free solders. The single layer weave used for Soder-Wick Lead-Free braid is lighter in mass than any other desoldering braid available and allows for lead-free solder removal at lower temperatures. Soder-Wick Lead-Free responds faster than any other conventional desoldering braid. This unique design minimizes overheating and requires less "contact" time thus preventing heat damage to the PCB and sensitive components. For Lead-Free rework, Soder-Wick has the answer.

- Fastest wicking and heat transfer
- High capacity for solder uptake
- Halide free, no corrosive residues
- Minimizes risk of heat damage to pads, components and PBCs
- Can be used with Tin/Lead solders
- RoHS compliant

Typical Applications

Soder-Wick Lead-Free desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals, Lugs and Posts
- Identification Script



Typical Product Data and Physical Properties

Flux Type:	High-Temperature No Clean Type ROL0
Specifications:	ANSI/IPC J STD-004 MIL-F-14256 F
No Clean Flux Spec:	MIL-STD-883B Bellcore TR-NWT-000078 ANSI/IPC J SF818
Shelf Life:	2 years
RoHS Compliant	Yes

Size #	Size Inches	Color	Size Metric
1	.030"	White/Gray	0.8mm
2	.060"	Yellow	1.5mm
3	.080"	Green	2.0mm
4	.110"	Blue	2.8mm

Static Dissipative Packaging

Soder-Wick Lead-Free is packaged on Static Dissipative bobbins to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B and meet the static delay rate provision of MIL-B-81705C

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Usage Instructions

For industrial use only. Read SDS carefully prior to use.

- 1) Choose a Soder-Wick® Lead-Free braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F.
- 4) Place wick on solder joint and place tip of hot iron on top of wick.
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard used portion of the wick
- 9) If needed, clean PCB with CircuitWorks Lead-Free Flux Remover Pen CW9400 and remove soils with a ControlWipes absorbent wipe.

Soder-Wick Is Designed To Meet or Exceed the Following:

- MIL-F-14256F, Type R
- NASA-STD-8739.3
- DOD-STD-883E, Method 2022
- ANSI/IPC J STD-004, Type ROL0
- BELLCORE TR-NWT-000078
- ANSI/IPC J SF-818

Soder-Wick Bobbins Are Designed To Meet or Exceed:

- MIL-STD-2000A
- MIL-B-81705C
- MIL-STD-1686C
- MIL-HDBK-263B
- ANSI/IPC J SF-818

Availability

25 bobbins / bag

Part #	Size #	Length	Part #	Size	Length
40-1-5	1	5			
40-2-5	2	5	40-2-10	2	10
40-3-5	3	5	40-3-10	3	10
40-4-5	4	5	40-4-10	4	10

Resealable Packaging	Part #	Size
	SW140255	2
	SW14035	3
	SW14045	4

The resealable bag contains ten five-foot bobbins. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

Technical and Application Assistance

Chemtronics provides a technical hotline to answer your technical and application related questions.

The toll free number is: 1-800-TECH-401.

Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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